

0

10

20

Temperature

30



Product Features: Low Cost SMD Package RoHs Compliant Compatible with Leadfree Processing	Applications: Real Time Clocks Metering Industrial Control Time Reference	4.1	
Frequency	32.768 KHz		
ESR (Equivalent Series Resistance)	70 KΩ Max.	╶┰┕─────┙╆╴	
Shunt Capacitance (C0)	1.0 pF Typical	T T 0.9 0.20	
Frequency Tolerance @ 25° C	±20 ppm Standard	Max. 0.20	
Frequency Stability over Temperature	Parabolic $-0.034 \text{ ppm} / \circ \text{C}^2$ Typical. Inflection point approx. 27° C See Graph Below		
Crystal Cut	X-Cut	0.15	
Load Capacitance	12.5 pF Standard		
Drive Level	1 uW Max.		
Aging	\pm 5 ppm Max. / Year Standard		
Temperature		0.8	
Operating	-40° C to +85° C Standard (
Storage	-40° C to +85° C Standard	Pad Layout	
Typical X -30 -30 -30 -30 -30 -30 -30 -30			

Sample Part Number: IL3Y - HX5F12.5 - 32.768 KHz

80

70

Package	Stability (ppm) at Room Temperature	Stability (ppm) over Operating Temperature	Operating Temperature Range	ode (overtone)	Load Capacitance (pF)	Frequency
IL3Y -	H = ±20 ppm	X = X Cut	5 = -40°C to +85°C	F = Fundamental	12.5 pF Standard 6.0 pF Available	- 32.768 KHz

50

40

60



-40

Part Number Guide

-30

-20

-10

Dimension Units: mm



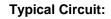
2 Pad Glass Package Quartz Crystal, 1.5 mm x 4.1 mm



Rlimit

С2

Pb Free Solder Reflow Profile:

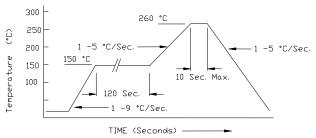


C1

 \mathcal{M}

Crystal

Rf

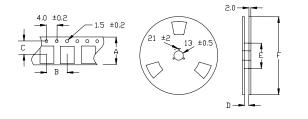


*Units are backward compatible with 240C reflow processes

Package Information:

MSL = 2a Termination = e4 (Au over Ni over W base metal)

Tape and Reel Information:



Quantity per Reel	3000	
A	12 +/3	
В	8 +/2	
С	5.5 +/2	
D	13.5 +/-1 or 12 +/- 3	
E	60 / 80	
F	180 / 250	

Environmental Specifications

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

Marking

Line 1: Frequency, Date Code



